



Supplemental Application Data Sheet

Application Information

Application Number:: 10/618,985
Filing Date:: 07/14/03
Application Type:: Regular
Subject Matter:: Utility
Title:: THERMOPLASTIC MOLDING PROCESS
Attorney Docket Number:: JETTA-003US
Request for Early Publication?:: No
Request for Non-Publication?:: No
Total Drawing Sheets:: 2
Small Entity?:: No
Petition included?:: No
Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority type:: Inventor
Primary Citizenship Country:: CN
Status:: Full Capacity
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Representative Information

Representative Customer Number::	28156	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non- Provisional of	60/409,217	09/09/02

Assignment Information

Assignee name:: J.T. LABS, LTD.

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